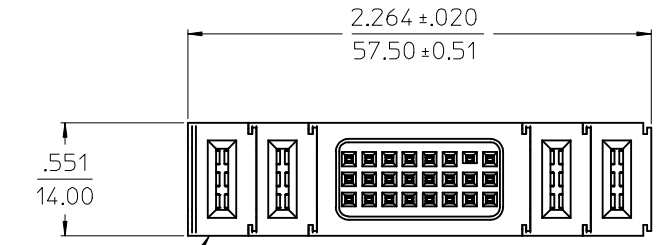
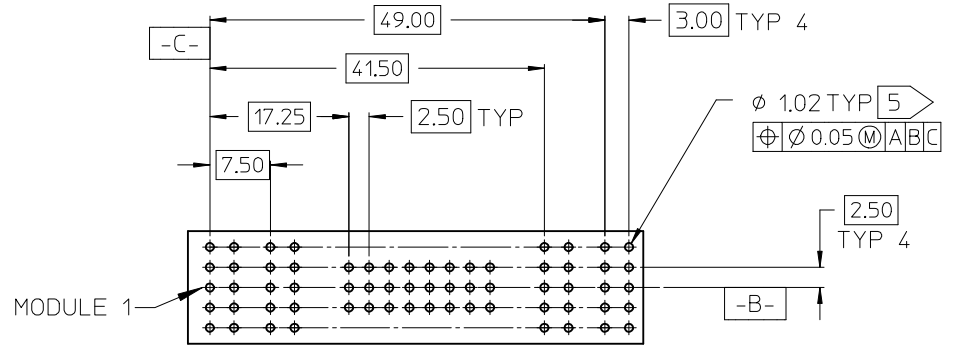
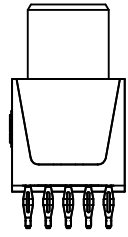
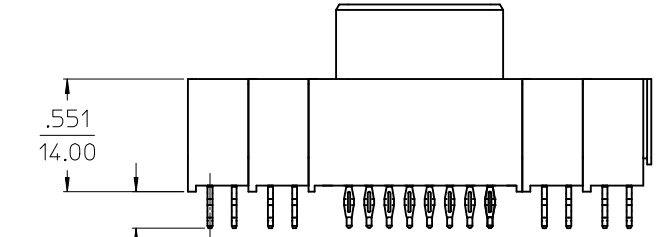


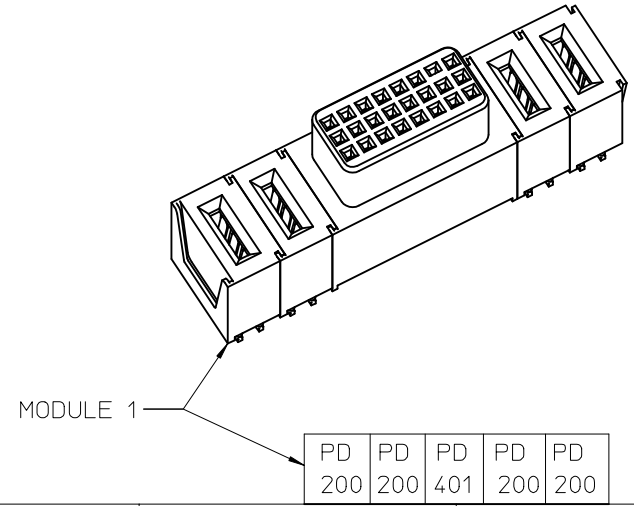
- NOTES:
1. MATERIAL: LCP, GLASS FILLED, UL94V-0, BLACK.
CONTACTS: COPPER ALLOY
 2. FINISH: SELECT GOLD: 30 MI MIN.
SELECT TIN: 100 MI MIN.
BOTH OVER NICKEL
 3. PRODUCT SPECIFICATION: PS-45424-001.
 4. PACKAGING SPECIFICATION: PK-45484-001.
 5. PCB HOLE SPECIFICATION: PS-45424-001.



MODULE 1



MODULE 1



MODULE 1

PCB LAYOUT: COMPONENT SIDE
PCB THICKNESS: .093/2.36
PCB TOLERANCE: ±.002/0.05

GEOM TOL PCB	DESCRIPTION	EC NO: UCP2005-2724
		DRWN: ADRA1N02005/07/07
REV	REV	CH'KD: KSAMIEC 2005/07/08
		APPR: APATEL 2005/08/17
D1		

GENERAL TOLERANCES (UNLESS SPECIFIED)	
	mm INCH
4 PLACES	± --- ± ---
3 PLACES	± --- ± .010
2 PLACES	± 0.25 ± .015
1 PLACE	± 0.38 ± ---
ANGULAR ±1/2°	
DRAFT WHERE APPLICABLE	
MUST REMAIN WITHIN DIMENSIONS	

SCALE	DESIGN UNITS
1:1	METRIC
DIMENSION STYLE	
IN/MM	
DRAWN BY	DATE
SAMIEC	2003/03/25
CHECKED BY	DATE
MARGULIS	2003/03/25
APPROVED BY	DATE
MARGULIS	2003/03/25
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

THIRD ANGLE PROJECTION	REVISE ON CAD ONLY
TITLE	
POWER DOCK ASSEMBLY SOCKET VERTICAL CPI	
molex MOLEX INCORPORATED	
MATERIAL NO.	DOCUMENT NO.
45484-0003	SD-45484-003
SHEET NO.	1 OF 1